# EAST Search History

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|---|---|---|---|---|---|---|
| L1 | 1319 | 174/254.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/12/05 04:40 |
| L2 | 49 | "4814855" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/12/05 04:43 |
| L3 | 2 | ("4814855").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2008/12/05 04:43 |
| L4 | 2 | ("5859471").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2008/12/05 04:44 |
| L5 | 147 | "4707724" \| "5311056").PN. OR ("5859471").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/12/05 04:46 |
| L6 | 21 | "5357400" | US-PGPUB; USPAT; USOCR | OR | ON | 2008/12/05 04:50 |
| L7 | 2 | ("5357400").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2008/12/05 04:50 |
| L8 | 2 | ("6992372").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2008/12/05 04:51 |
| L9 | 3 | ("6320135").PN. OR ("6992372").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/12/05 04:52 |
| L10 | 1 | "10519144" | US-PGPUB; USPAT; USOCR | OR | ON | 2008/12/05 05:02 |
| L11 | 12 | "6320135" | US-PGPUB; USPAT; USOCR | OR | ON | 2008/12/05 05:07 |
| L12 | 2 | ("6320135").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2008/12/05 05:08 |

| L13 | 2 | ("20050056915").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2008/12/05 05:19 |
|---|---|---|---|---|---|---|
| L14 | 1 | ("2005/0056915").URPN. | USPAT | OR | ON | 2008/12/05 05:20 |
| L15 | 6 | ("20050056915" \| "20050121779" \| "20050186702" \| "20050194693" \| "20060103027" \| "6992372").PN. OR ("7282389").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/12/05 05:20 |
| L16 | 6 | "6,262,473" | US-PGPUB; USPAT; USOCR | OR | ON | 2008/12/05 06:23 |
| L17 | 2 | ("6,262,473").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2008/12/05 06:23 |
| L18 | 1 | ("6320135").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/12/05 06:32 |
| L19 | 7 | ("4177519" \| "5338973" \| "5585675" \| "5820952" \| "5996768" \| "6180215" \| "6201194").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/12/05 06:33 |
| L20 | 1315 | 174/250.ccls. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/12/05 06:33 |
| L21 | 5 | 20 and dummy adj wiring | US-PGPUB; USPAT; USOCR | OR | ON | 2008/12/05 06:34 |
| L22 | 18 | sprocket adj holes and dummy adj wiring | US-PGPUB; USPAT; USOCR | OR | ON | 2008/12/05 06:35 |
| L23 | 2 | 20 and 22 | US-PGPUB; USPAT; USOCR | OR | ON | 2008/12/05 06:35 |
| L25 | 1 | "20040004823" | USPAT | OR | ON | 2008/12/05 06:38 |
| L26 | 13 | "6572780" | USPAT | OR | ON | 2008/12/05 06:42 |
| L27 | 2 | ("6572780").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2008/12/05 06:42 |
| L28 | 21 | sprocket adj holes and dummy near2 wiring | US-PGPUB; USPAT; USOCR | OR | ON | 2008/12/05 06:44 |
| L29 | 5369 | sprocket adj holes | US-PGPUB; USPAT; USOCR | OR | ON | 2008/12/05 06:44 |
| L30 | 589 | dummy adj wiring | US-PGPUB; USPAT; USOCR | OR | ON | 2008/12/05 06:45 |
| L31 | 18 | 29 and 30 | US-PGPUB; USPAT; USOCR | OR | ON | 2008/12/05 06:45 |

| L32 | 2 | ("20010045651" \| "20030020163").PN. OR ("6958288").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/12/05 06:48 |
|-----|-----|-----|-----|-----|-----|-----|
| L33 | 1 | "20040238968" | US-PGPUB; USPAT; USOCR | OR | ON | 2008/12/05 06:51 |
| L34 | 2 | "20040004823" | US-PGPUB; USPAT; USOCR | OR | ON | 2008/12/05 07:28 |
| L36 | 310 | sprocket adj holes and concave | US-PGPUB; USPAT; USOCR | OR | ON | 2008/12/05 08:24 |
| L37 | 194322 | ("printed circuit board" or "PCB") | US-PGPUB; USPAT; USOCR | OR | ON | 2008/12/05 08:25 |
| L38 | 12 | 36 and 37 | US-PGPUB; USPAT; USOCR | OR | ON | 2008/12/05 08:25 |
| L39 | 1003 | 361/749.ccls. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/12/05 08:41 |
| L40 | 2 | 39 and sprocket adj holes and dummy adj wiring | US-PGPUB; USPAT; USOCR | OR | ON | 2008/12/05 08:43 |
| S2 | 2546 | housing with gap and shielding | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/07 16:00 |
| S6 | 58 | S2 and burst | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/07 16:02 |
| S7 | 31 | S2 and burst and ground | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/07 16:02 |
| S8 | 42 | S2 and TVS | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/07 16:02 |
| S9 | 4 | S7 and S8 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/07 16:02 |
| S10 | 2386 | ELECTRONIC adj DEVICE and ESD | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/07 16:04 |
| S11 | 3 | S10 and burst same TVS | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/07 16:05 |

| S12 | 776762 | electronic adj device and joint or layer and circuit adj board and IC or integrated adj circuit | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/07 16:41 |
|-----|--------|---|---|---|---|---|
| S13 | 22312 | S12 and ground and housing | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/07 16:43 |
| S14 | 3108 | S13 and shielding | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/07 16:43 |
| S15 | 88 | S14 and 361/818.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/07 16:43 |
| S16 | 11 | S15 and capacitor and ESD | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/07 16:44 |
| S17 | 2386 | electronic adj device and ESD and electronic adj device | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/07 16:51 |
| S20 | 772 | 361/88.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/07 17:06 |
| S21 | 1991 | 361/818.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/07 17:06 |
| S22 | 1 | S21 and housing adj seam and IC | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/07 17:07 |
| S28 | 66 | S21 and housing and IC | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/07 17:09 |
| S30 | 85511 | housing and gap and shielding adj unitground burst | USPAT | OR | ON | 2008/04/07 17:53 |

| S31 | 2 | housing and gap and shielding adj unit and ground and burst | USPAT | OR | ON | 2008/04/07 17:53 |
|-----|-----|-----|-----|-----|-----|-----|
| S32 | 13 | ("3073916" \| "3670299" \| "4115667" \| "4187502").PN. OR ("5012457").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/04/07 17:54 |
| S33 | 154 | shield$4 same esd same (printed pcb) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/08 10:20 |
| S34 | 92 | S33 same ground$4 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/08 10:20 |
| S35 | 21 | S34 same (opening aperture hole window) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/08 10:22 |
| S36 | 33 | S33 same (opening aperture hole window) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/08 10:23 |
| S37 | 21 | S36 and S35 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/08 10:24 |
| S38 | 1052 | 361/212.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/08 10:29 |
| S40 | 3 | S33 and S38 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/08 10:30 |
| S41 | 29 | S34 same (opening aperture hole window gap) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/08 13:27 |
| S42 | 2 | "20060023387" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/08 13:36 |

| S43 | 2 | "20060012969" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/08 13:38 |
|-----|-----|-----|-----|-----|-----|-----|
| S44 | 5086 | antiFuse | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/08 14:24 |
| S48 | 2 | "20060172573" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/08 16:36 |
| S51 | 9 | notebook and housing and ESd and filter and shielding and ground | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/08 16:45 |
| S52 | 1919339 | electronic adj device and ESD and housing and gap and shielding and component filter | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/08 16:55 |
| S53 | 39 | electronic adj device and ESD and housing and gap and shielding and component and filter | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/08 16:55 |
| S55 | 13877 | housing and gap and shielding | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/08 17:17 |
| S56 | 5196 | S55 and ground | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/08 17:17 |
| S57 | 5196 | S56 and shielding | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/08 17:18 |
| S58 | 228 | S57 and TVS | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/08 17:19 |
| S59 | 33 | (shield$4 same esd same (printed pcb) same (opening aperture hole window)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/08 17:40 |

| S60 | 558764 | "33" and filter | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/08 17:40 |
|-----|--------|-----------------|---------------------------------------------------|----|-----|-------------------|
| S61 | 1 | S59 and filter | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/08 17:40 |
| S62 | 17 | "4801273" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/09 10:37 |
| S63 | 2 | ("4801273").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2008/04/09 10:37 |
| S64 | 1002418 | nootbook and housing and ESd and filter and shielding and ground and gap window | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/09 13:36 |
| S65 | 2388 | ELECTRONIC adj DEVICE and ESD | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/09 14:34 |
| S66 | 41 | S65 and PDA and notebook and mobile adj phone | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/09 14:39 |
| S67 | 2 | "20020048156" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/09 19:08 |
| S69 | 2 | "20050009381" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/09 19:15 |
| S70 | 3 | 2004/0183209 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/10 09:18 |
| S72 | 2 | ("20040183209").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2008/04/10 09:18 |

| S74 | 17 | built near in near capacitor | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2008/04/10 09:26 |
| S76 | 13 | built near in near capacitor and power | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/10 09:26 |
| S77 | 9 | S76 and pad | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/10 09:34 |
| S78 | 9 | S77 and power | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/10 09:36 |
| S79 | 697 | APPARATUS and INTERCONNECTING and BALL adj GRID adj ARRAY and PRINTED adj CIRCUIT adj BOARD | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2008/04/10 09:55 |
| S80 | 0 | S79 and power adj bar | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2008/04/10 09:57 |
| S81 | 82 | S79 and bar | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/10 09:57 |
| S82 | 11 | S81 and power adj supply | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/10 09:57 |
| S83 | 1543 | 361/816.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/10 13:58 |
| S84 | 669 | 361/800.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/10 14:04 |
| S85 | 875 | 361/803.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/10 14:04 |

| S86 | 9 | S83 and S84 and S85 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/10 14:04 |
| S87 | 199405 | @ad<="20040415" and ("PCB" or "printed circuit board") with shield and ground adj layer and electromagnetic adj radiation and via metal adj layer | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/10 14:11 |
| S88 | 2068 | S87 and polymer adj substrate | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/10 14:13 |
| S90 | 29 | S88 and flange and ground | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/10 14:13 |
| S91 | 486 | 174/377.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/10 14:16 |
| S92 | 4 | S88 and S91 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/10 14:16 |
| S93 | 2225371 | S90 and mechanical adj connector and ground adj plane and via or window or aperture | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/10 14:18 |
| S94 | 7 | S90 and mechanical adj connector and ground adj plane and via | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/10 14:18 |
| S95 | 3 | S90 and mechanical adj connector and ground adj plane and via and metallized adj polymer | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/10 14:19 |
| S96 | 3 | "20060094296" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/10 16:23 |

| S97 | 9 | "6712544" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/10 16:30 |
|-----|-----|-----|-----|-----|-----|-----|
| S98 | 3 | ("6712544").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2008/04/10 16:31 |
| S99 | 20 | ("2447299" \| "3316798" \| "3413886" \| "3468091" \| "4367053" \| "5288191" \| "5419650" \| "5895189" \| "6071036" \| "6487882").PN. OR ("6712544").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/04/10 16:35 |
| S100 | 14110 | @ad<="20050429" and ("PCB" or "printed circuit board" or substrate) with chip same pad and ground adj layer and insulativeand passive and grooves | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/10 18:13 |
| S101 | 30 | 174/661.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/10 18:13 |
| S102 | 175 | "5353498" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/11 09:27 |
| S103 | 2 | ("5353498").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2008/04/11 09:28 |
| S104 | 54 | packaging adj substrate and array and chip adj pad | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/11 09:38 |
| S105 | 54 | S104 and chip | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/11 09:39 |
| S106 | 6925353 | S105 and via window open$3 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/11 09:39 |

| S107 | 36 | S105 and via | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/11 09:40 |
|------|-----|---------------|------------------------------------------------|-----|-----|-------------------|
| S109 | 1 | S104 and overflow near preventive | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/11 09:41 |
| S111 | 14040 | chip near pad | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/11 09:42 |
| S112 | 54 | packaging adj substrate and array and chip adj pad and S111 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/11 09:42 |
| S113 | 77 | packaging adj substrate and chip adj pad and S111 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/11 09:42 |
| S114 | 2 | S113 and overflow near preventive | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/11 09:42 |
| S115 | 2 | "overflow-preventive grooves" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/11 09:53 |
| S116 | 4 | "overflow-preventive" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/11 09:55 |
| S117 | 48 | "2763403" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/11 09:56 |
| S119 | 118 | packaging adj substrate and chip near pad | USPAT | OR | ON | 2008/04/11 10:01 |
| S120 | 311451 | packaging adj substrate and chip near pad and overflownear grooves | USPAT | OR | ON | 2008/04/11 10:01 |
| S124 | 8 | packaging adj substrate and chip near pad and grooves | USPAT | OR | ON | 2008/04/11 10:02 |

| S125 | 4 | "overflow-preventive" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/11 10:04 |
| S126 | 198522 | "overflow" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/11 10:04 |
| S127 | 1 | S104 and S126 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/11 10:05 |
| S128 | 50 | S126 and array and chip adj pad | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/11 10:05 |
| S129 | 5 | S128 and grooves | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/11 10:06 |
| S130 | 272 | @ad<="20040924" and ("PCB" or "printed circuit board") with insulating adj substrate and capacitor and insulating adj substrate | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/11 11:34 |
| S131 | 85 | S130 and conductive adj layer | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/11 11:35 |
| S132 | 9758 | S131 conductive adj circuit | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/11 11:36 |
| S134 | 1 | S131 and conductive near circuit | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/11 11:36 |
| S135 | 64 | @ad<="20040924" and ("PCB" or "printed circuit board") with insulating adj substrate and capacitor and insulating adj substrate and resistors and capacitors and conductive adj layer | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/11 11:53 |

| S136 | 52 | S135 and integrated adj circuit | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/11 11:54 |
| S137 | 21 | S136 and electrodes and capacitor | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/11 11:54 |
| S138 | 8 | "6,948,940" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/14 10:31 |
| S139 | 2 | ("6,948,940").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2008/04/14 10:31 |
| S140 | 2 | ("11116066").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2008/04/14 10:48 |
| S141 | 3 | "11116066" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/14 10:49 |
| S142 | 8 | "6948940" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/14 11:10 |
| S143 | 2 | ("6948940").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2008/04/14 11:10 |
| S144 | 1317 | 174/254.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/12/01 10:48 |
| S145 | 7 | "6,262,473" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/12/01 10:49 |
| S146 | 2 | ("6,262,473").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2008/12/01 10:50 |

| S147 | 2 | ("20030107120").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2008/12/01 14:24 |

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